

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TLC27M2ACD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
TLC27M2ACDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
TLC27M2ACP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2ACPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2AID	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
TLC27M2AIDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
TLC27M2AIP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2AIPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2BCD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC27M2BCDG4	ACTIVE	SOIC	D	8	75	TBD	Call TI	Call TI
TLC27M2BCDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC27M2BCP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2BCPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2BCPSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
TLC27M2BID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC27M2BIDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC27M2BIDRG4	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI
TLC27M2BIP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2BIPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2CD	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
TLC27M2CDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
TLC27M2CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2CPSLE	OBSOLETE	SO	PS	8		TBD	Call TI	Call TI
TLC27M2CPSR	ACTIVE	SO	PS	8	2000	TBD	CU NIPDAU	Level-1-220C-UNLIM
TLC27M2CPW	ACTIVE	TSSOP	PW	8	150	TBD	CU NIPDAU	Level-1-220C-UNLIM
TLC27M2CPWLE	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TLC27M2CPWR	ACTIVE	TSSOP	PW	8	2000	TBD	CU NIPDAU	Level-1-220C-UNLIM
TLC27M2ID	ACTIVE	SOIC	D	8	75	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
TLC27M2IDR	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
TLC27M2IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M2IPW	ACTIVE	TSSOP	PW	8	150	TBD	CU NIPDAU	Level-1-220C-UNLIM
TLC27M2IPWR	ACTIVE	TSSOP	PW	8	2000	TBD	CU NIPDAU	Level-1-220C-UNLIM
TLC27M2MD	ACTIVE	SOIC	D	8	75	TBD	CU NIPDAU	Level-1-220C-UNLIM
TLC27M2MDR	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI
TLC27M2MFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TLC27M2MJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TLC27M2MJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TLC27M7CD	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC27M7CDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC27M7CP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M7CPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M7CPSR	ACTIVE	SO	PS	8	2000	Pb-Free (RoHS)	CU NIPDAU	Level-2-260C-1YEAR/ Level-1-220C-UNLIM
TLC27M7ID	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC27M7IDR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC27M7IDRG4	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI
TLC27M7IP	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M7IPE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
TLC27M7MFKB	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
TLC27M7MJG	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TLC27M7MJGB	OBSOLETE	CDIP	JG	8		TBD	Call TI	Call TI
TLC27M7MUB	OBSOLETE	CFP	U	10		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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